

C. Amendments to the Claims

1-13 (canceled).

AZ
Sub
B1

14 (original): A device comprising:
a component;
a heat sink attached to the component, the heat sink having at least one cutout and having an overhang on all sides of the component; and
a clip in contact with the component and the heat sink, the clip having a polygonal frame and a portion that extends through the at least one cutout, the portion of the clip attaching the component to the heat sink.

[15 (canceled).]

16 (new): The device of Claim 14 wherein:
the overhang is symmetric.

17 (new): The device of Claim 14 wherein:
the component has four sides;
the polygonal frame also four sides; and
each side of the polygonal frame is substantially parallel to a corresponding side of the component.

18 (new): The device of Claim 14 wherein:
the heat sink has a lower surface attached to the component;
the heat sink has an upper surface opposite to the lower surface; and
the heat sink comprises a plurality of protrusions located on the upper surface.

SILICON VALLEY
PATENT GROUP, LLP
2350 Mission College Blvd.
Suite 360
Santa Clara, CA 95054
(408) 982-8200
FAX (408) 982-8210

19 (new): The device of Claim 18 wherein:
a group of said protrusions are located in a central region of the upper surface of the heat sink;
the remainder of said protrusions are located in an outer annular region of the heat sink that is separated from the central region by an inner annular region of the heat sink; and
the inner annular region of the heat sink is devoid of protrusions.

20 (new): The device of Claim 19 wherein:
the polygonal frame of the clip has a lower surface in contact with the upper surface of the heat sink in the inner annular region.

21 (new): The device of Claim 19 wherein:
the polygonal frame has four sides;
the inner annular region of the heat sink also has four sides; and
each side of the polygonal frame is in contact with a corresponding side of the inner annular region.

22 (new): The device of Claim 21 wherein:
the polygonal frame has an upper surface opposite to the lower surface of the polygonal frame; and
a thickness of the polygonal frame between the upper surface and the lower surface thereof is smaller than a height of a protrusion in said plurality of protrusions.

23 (new): The device of Claim 19 wherein:

SILICON VALLEY
PATENT GROUP LLP
2330 Mission College Blvd.
Suite 360
Santa Clara, CA 95054
(408) 982-8210
FAX (408) 982-8210

said "at least one cutout" is a round hole located in the inner annular region of the heat sink; and

the clip has a rod with a round cross section that passes through the round hole.

24 (new): The device of Claim 23 wherein:

the heat sink has a plurality of additional holes also located in the inner annular region; and

the clip has a plurality of additional members that pass through the additional holes in the heat sink.

25 (new): The device of Claim 19 wherein:

among the remainder of said protrusions located in the outer annular region of the heat sink, there are at least two rows on at least one side of the heat sink.

26 (new): The device of Claim 25 wherein:

there are at least two rows on all sides of the heat sink, including said at least one side.

27 (new): The device of Claim 25 wherein:

at least one of the protrusions in the at least two rows is a cooling fin.

28 (new): The device of Claim 25 wherein:

at least one of the protrusions in the at least two rows is a cooling pin.

29 (new): The device of Claim 18 wherein:

the polygonal frame of the clip has an upper surface that is exposed;

SILICON VALLEY
PATENT GROUP LLP
2350 Mission College Blvd.
Suite 360
San Jose, CA 95128
(408) 982-8200
FAX: (408) 982-8210

the polygonal frame has a lower surface that is opposite to the exposed upper surface;

the lower surface of the polygonal frame is in contact with an annular region on the upper surface of the heat sink;

the polygonal frame surrounds a group of said protrusions located in a central region of the upper surface of the heat sink; and

the component has an upper surface that is attached to a central region of a lower surface of the heat sink

30 (new): A device comprising:

a component;

a heat sink attached to the component, the heat sink having an overhang on all sides of the component, the heat sink comprising a plurality of protrusions located on an upper surface thereof; and

a clip in contact with the component and the heat sink, the clip having a portion that extends through an opening in the heat sink, the portion of the clip attaching a lower surface of the heat sink to the component.

31 (new): The device of Claim 30 wherein:

a group of said protrusions are located in a central region of the upper surface of the heat sink;

the remainder of said protrusions are located in an outer annular region of the heat sink that is separated from the central region by an inner annular region of the heat sink;

the inner annular region of the heat sink is devoid of protrusions; and

the clip rests in the inner annular region and surrounds the group of said protrusions located in the central region of the heat sink.

SILICON VALLEY
PATENT GROUP LLP
2350 Mainline Circle, Suite 360
Santa Clara, CA 95054
(408) 982-8210
FAX (408) 982-8210

32 (new): The device of Claim 31 wherein:

among the remainder of said protrusions located in the outer annular region of the heat sink, there are at least two rows on at least one side of the heat sink, and at least one of the protrusions is either a cooling fin or a cooling pin.

33 (new): The device of Claim 30 wherein:

said opening is a round hole located in the inner annular region of the heat sink; and

the clip has a rod with a round cross section that passes through the round hole.

34 (new): The device of Claim 33 wherein:

the heat sink has a plurality of additional holes also located in the inner annular region; and

the clip has a plurality of additional members that pass through the additional holes in the heat sink.

35 (new): A device comprising:

a component;

a heat sink attached to the component, the heat sink having at least one cutout and having an overhang on all sides of the component, the heat sink comprising a group of protrusions located in a central region of the heat sink; and

a clip comprising a polygonal frame that surrounds the group of protrusions on all sides, the clip further comprising a portion that extends through an opening in the heat sink, the portion of the clip attaching the component to the heat sink.

SILICON VALLEY
PATENT GROUP LLP
3390 Midway College Blvd.
Suite 300
San Jose, CA 95134
(408) 982-8200
FAX (408) 982-8210

36 (new): The device of Claim 35 wherein:

additional protrusions are located in an outer annular region of the heat sink separated from said group of protrusions by an inner annular region of the heat sink; and

the inner annular region of the heat sink is devoid of protrusions.

37 (new): The device of Claim 36 wherein:

the polygonal frame of the clip has a lower surface in contact with the upper surface of the heat sink in the inner annular region.

38 (new): The device of Claim 36 wherein:

the polygonal frame has four sides;

the inner annular region of the heat sink also has four sides; and

each side of the polygonal frame is in contact with a corresponding side of the inner annular region.

39 (new): The device of Claim 38 wherein:

the polygonal frame has an upper surface opposite to the lower surface of the polygonal frame; and

a thickness of the polygonal frame between the upper surface and the lower surface thereof is smaller than a height of a protrusion.

40 (new): The device of Claim 36 wherein:

said opening is a round hole located in the inner annular region of the heat sink; and

the clip has a rod with a round cross section that passes through the round hole.

SILICON VALLEY
PATENT GROUP LLP
3350 Almaden College Blvd.
Suite 300
San Jose, CA 95128
(408) 982-8200
FAX (408) 982-8210

41 (new): The device of Claim 40 wherein:
the heat sink has a plurality of additional holes also located in the inner annular region; and

the clip has a plurality of additional members that pass through the additional holes in the heat sink.

42 (new): The device of Claim 36 wherein:
the additional protrusions form two rows on all sides of the heat sink, and each protrusion is either a fin or a pin.

43 (new): The device of Claim 35 wherein:
the polygonal frame of the clip has an upper surface that is exposed;
the polygonal frame has a lower surface that is opposite to the exposed upper surface;
the lower surface of the polygonal frame is in contact with an annular region on the upper surface of the heat sink; and
the component has an upper surface that is attached to a central region of a lower surface of the heat sink.

44 (new): A device comprising:
a component;
a heat sink attached to the component, the heat sink having at least one opening and having an overhang on all sides of the component;
a clip having a portion that extends through the opening in the heat sink, the portion of the clip attaching the heat sink to the component;
wherein
the heat sink has at least a group of protrusions, the group being surrounded on all sides by the clip; and

SILICON VALLEY
PATENT GROUP LLP

2320 Mission College Blvd.
Suite 360
Santa Clara, CA 95054
(408) 982-8200
FAX (408) 982-8210

the heat sink has additional protrusions that together surround the clip.

45 (new): The device of Claim 44 wherein:

the additional protrusions form two rows on all sides of the heat sink, and each protrusion is either a fin or a pin.

46 (new): The device of Claim 44 wherein:

the heat sink has a plurality of additional holes located between the group of protrusions and the additional protrusions; and

the clip has a plurality of additional members that pass through the additional holes in the heat sink.

SILICON VALLEY
PATENT GROUP LLP
1150 Mission College Blvd.
Suite 360
Santa Clara, CA 95054
(408) 982-8210
FAX (408) 982-8210